



## Material Content Data Sheet



Sales Product Name	BGF 120A E6327				Issued		29. August 2013	
MA#	MA000973748							
Package	PG-TSLP-4-8				Weight*		0.72 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.020	2.77	2.77	27738	27738
leadframe	non noble metal	nickel	7440-02-0	0.065	8.97	8.97	89718	89718
wire	noble metal	gold	7440-57-5	0.007	0.92	0.92	9249	9249
encapsulation	organic material	carbon black	1333-86-4	0.003	0.42		4213	
	plastics	epoxy resin	-	0.088	12.22		122155	
	inorganic material	silicondioxide	60676-86-0	0.517	71.62	84.26	716079	842447
leadfinish	noble metal	gold	7440-57-5	0.010	1.33	1.33	13348	13348
plating	noble metal	palladium	7440-05-3	0.003	0.42		4152	
	noble metal	gold	7440-57-5	0.010	1.33	1.75	13348	17500
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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